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(54) Title: IMPROVED WAFER-LIKE SENSOR

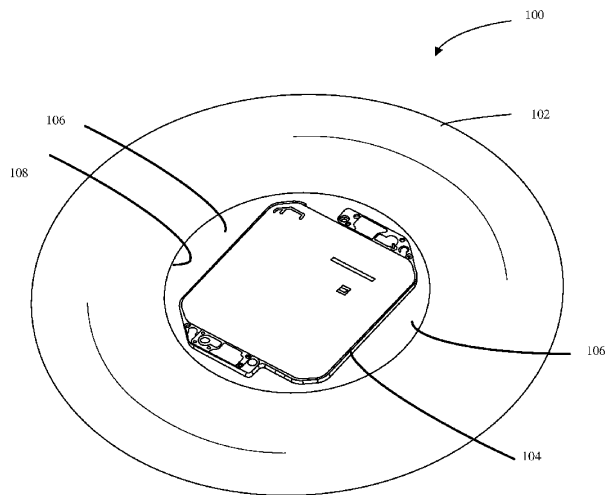


FIG. 1

(57) Abstract: A wafer-like semiconductor sensor (100, 200) includes a wafer-like base formed of a plurality of layers (112, 406, 110, 404) of chemically-hardened glass and an electronics module (104, 204) mounted to a recessed pocket (106) in the base and containing a sensor (217).

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